

## 1. General description

Silicon Carbide Schottky diode in a TO263 (D2PAK) plastic package, designed for high frequency switched-mode power supplies.



AEC - Q101 Qualified



## 2. Features and benefits

- New 6th Generation Technology
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- High Forward Surge Capability  $I_{FSM}$
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant
- AEC-Q101 qualified

## 3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives
- On board charger

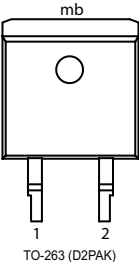
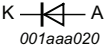
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
<b>Absolute maximum rating</b>							
$V_{RRM}$	repetitive peak reverse voltage			650			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 143$ °C; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		10			A
$T_j$	junction temperature			-55 to 175			°C
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>Static characteristics</b>							
$V_F$	forward voltage	$I_F = 10$ A; $T_j = 25$ °C; <a href="#">Fig. 5</a>		-	1.26	1.40	V
		$I_F = 10$ A; $T_j = 150$ °C; <a href="#">Fig. 5</a>		-	1.35	1.55	V
<b>Dynamic characteristics</b>							
$Q_r$	recovered charge	$I_F = 10$ A; $di_F/dt = 500$ A/ $\mu$ s; $V_R = 400$ V; $T_j = 25$ °C; <a href="#">Fig. 7</a>		-	24	-	nC

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	K	mounting base; connected to cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC6D10650BT2-A	TO263-2L	WNSC6D10650BT2-A6J	Reel	800	TO263N-2L	14-Oct-2022

## 7. Marking

Table 4. Marking codes

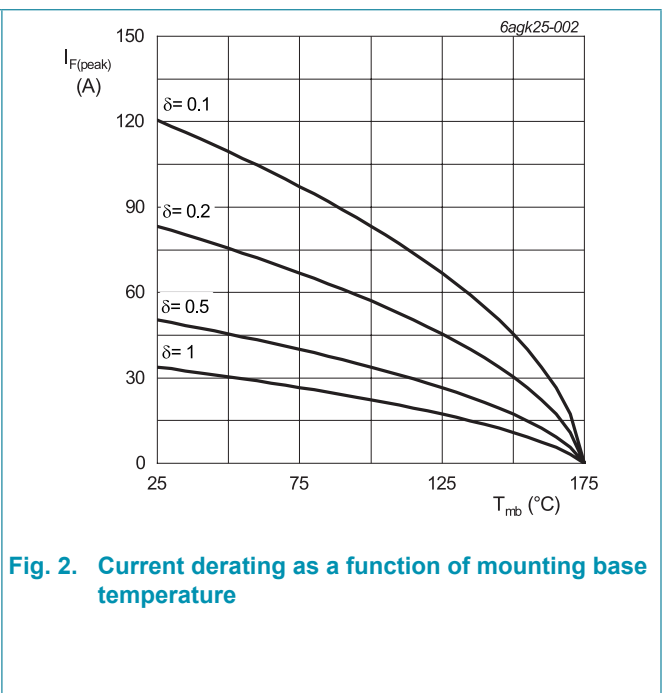
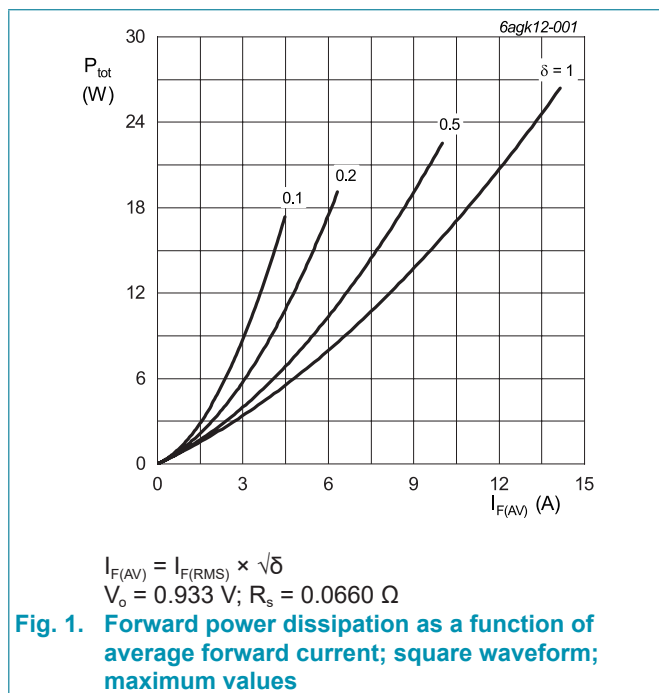
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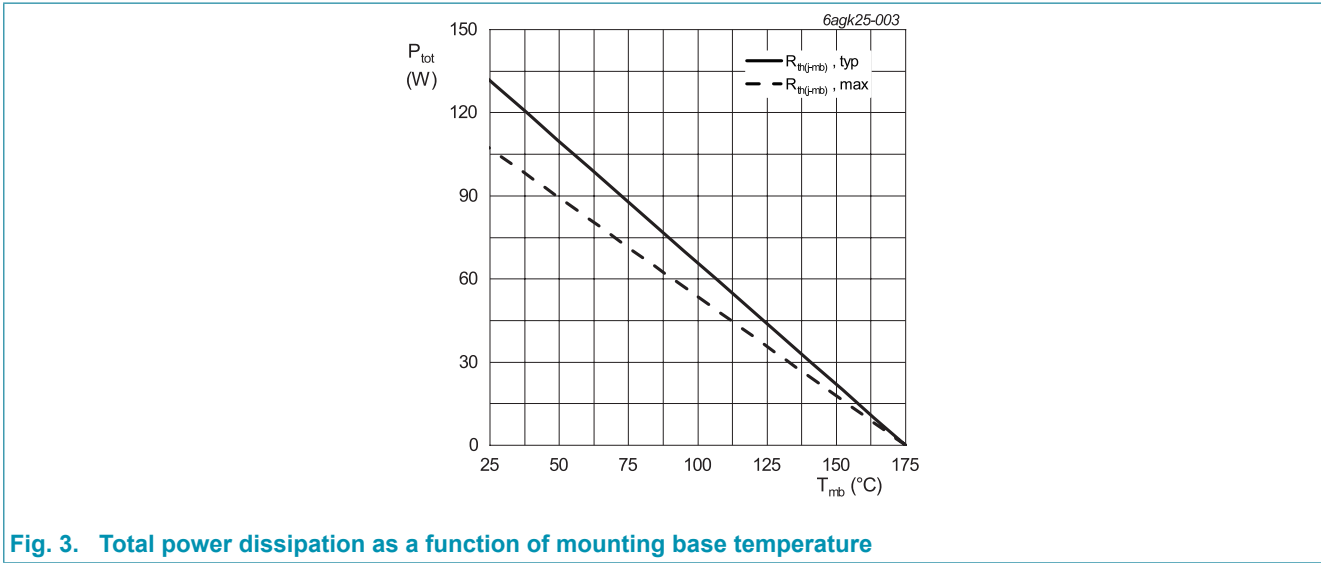
### 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage			650	V
$V_{RWM}$	crest working reverse voltage			650	V
$V_R$	reverse voltage	DC		650	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 143\text{ }^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		10	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{mb} \leq 143\text{ }^\circ\text{C}$ ; square-wave pulse		20	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse		75	A
		$t_p = 10\text{ }\mu\text{s}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; square-wave pulse		750	A
$I^2t$	$I^2t$ for fusing	sine-wave pulse; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; $t_p = 10\text{ ms}$		28.125	$\text{A}^2\text{s}$
$T_{stg}$	storage temperature			-55 to 175	$^\circ\text{C}$
$T_j$	junction temperature			-55 to 175	$^\circ\text{C}$





### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 4</a>		-	1.14	1.4	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W

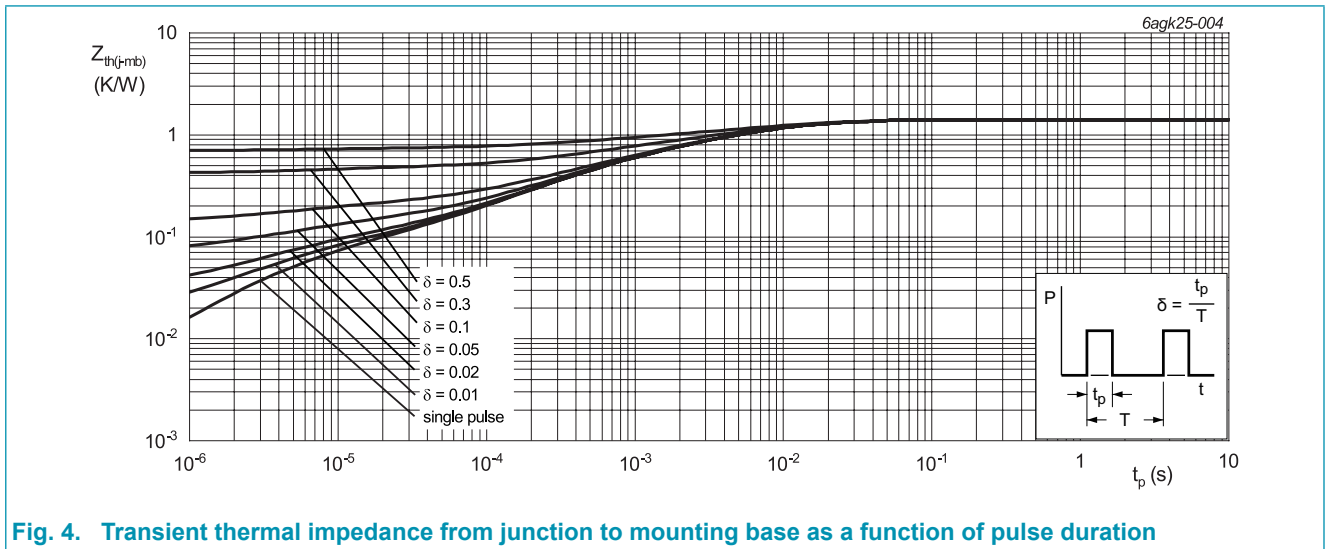
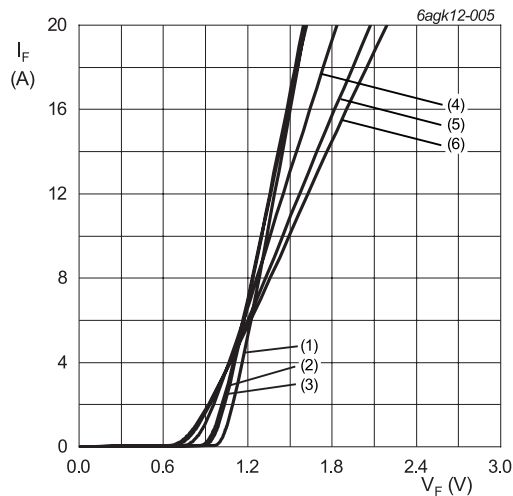


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

### 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>Static characteristics</b>							
$V_F$	forward current	$I_F = 10\text{ A}; T_J = 25\text{ °C}; \text{Fig. 5}$		-	1.26	1.40	V
		$I_F = 10\text{ A}; T_J = 150\text{ °C}; \text{Fig. 5}$		-	1.35	1.55	V
		$I_F = 10\text{ A}; T_J = 175\text{ °C}; \text{Fig. 5}$		-	1.40	1.60	V
$I_R$	reverse current	$V_R = 650\text{ V}; T_J = 25\text{ °C}; \text{Fig. 6}$		-	1	50	$\mu\text{A}$
		$V_R = 650\text{ V}; T_J = 175\text{ °C}; \text{Fig. 6}$		-	15	200	$\mu\text{A}$
<b>Dynamic characteristics</b>							
$Q_r$	recovered charge	$I_F = 10\text{ A}; V_R = 400\text{ V}; di_F/dt = 500\text{ A}/\mu\text{s}; T_J = 25\text{ °C}; \text{Fig. 7}$		-	24	-	nC
$C_d$	diode capacitance	$f = 1\text{ MHz}; V_R = 1\text{ V}; T_J = 25\text{ °C}$		-	500	-	pF
		$f = 1\text{ MHz}; V_R = 300\text{ V}; T_J = 25\text{ °C}$		-	58	-	pF
		$f = 1\text{ MHz}; V_R = 600\text{ V}; T_J = 25\text{ °C}$		-	52	-	pF
$E_{as}$	non-repetitive avalanche energy	$I_R = 5\text{ A}; L = 5\text{ mH}; T_{j(\text{init})} = 25\text{ °C}$		60	-	-	mJ



$V_o = 0.933\text{ V}; R_s = 0.0660\ \Omega$   
 (1)  $T_J = -55\text{ °C}$ ; typical values  
 (2)  $T_J = 0\text{ °C}$ ; typical values  
 (3)  $T_J = 25\text{ °C}$ ; typical values  
 (4)  $T_J = 100\text{ °C}$ ; typical values  
 (5)  $T_J = 150\text{ °C}$ ; typical values  
 (6)  $T_J = 175\text{ °C}$ ; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

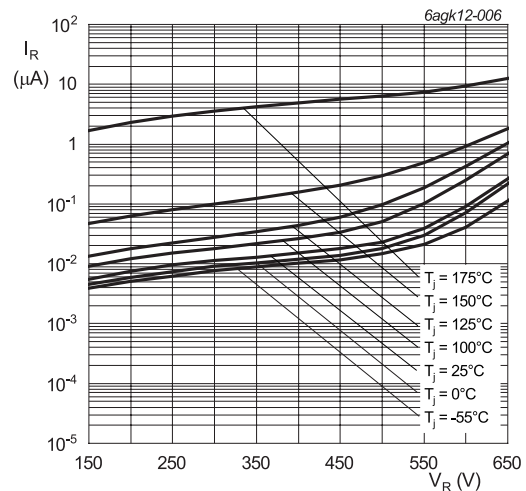


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

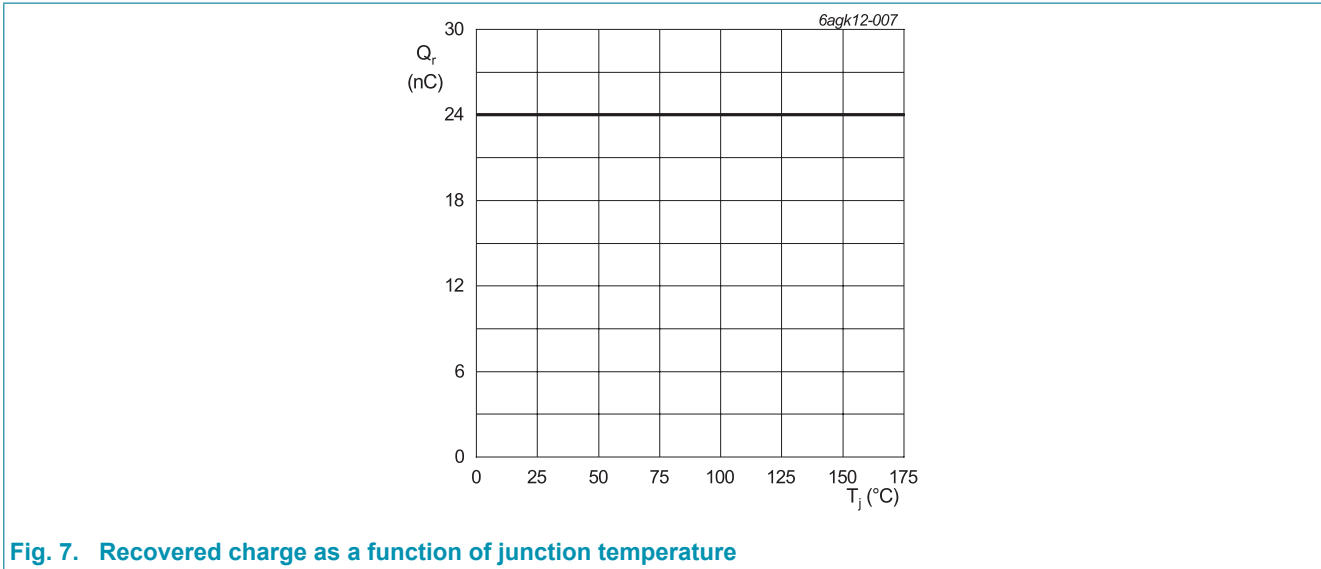
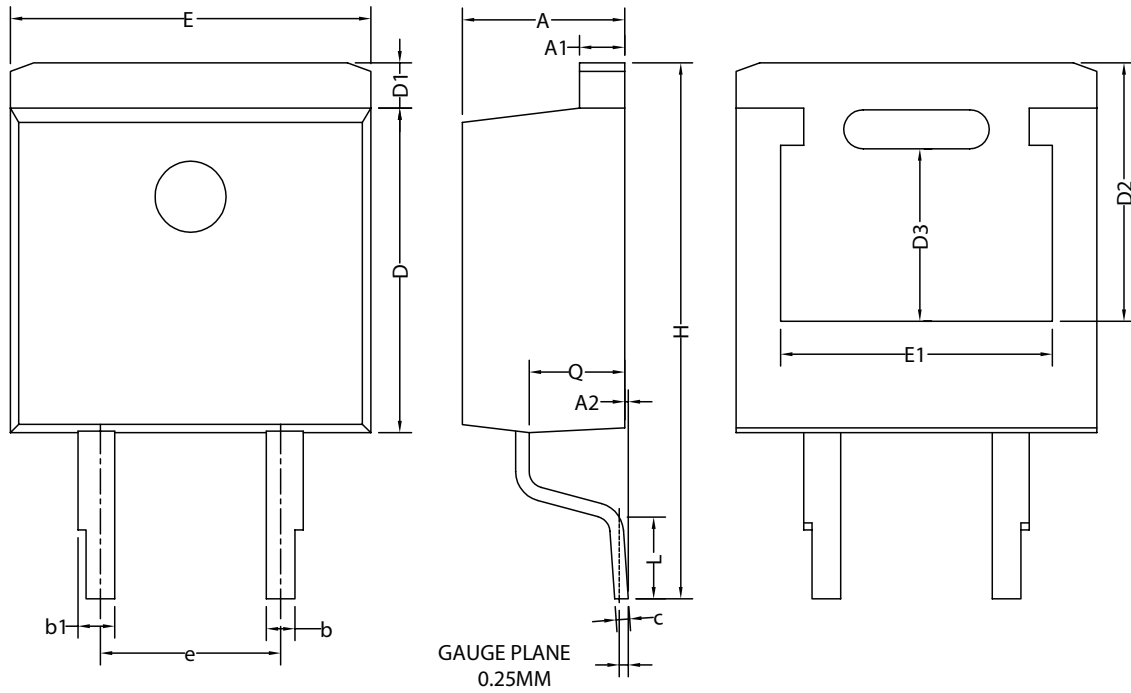


Fig. 7. Recovered charge as a function of junction temperature

### 11. Package outline

Plastic single-ended surface-mounted package (D2PAK); 2 leads

TO263-2L



Note:  
All dimensions do not include mold flash or protrusion.

Unit	A	A1	A2	b	b1	c	D	D1	D2	D3	e	E	E1	H	L	Q
MM	min	4.40	1.22	0.00	0.77	0.95	9.05	1.17	7.13	4.71	5.08 (BSC)	10.00	7.51	14.70	1.95	2.55
	max	4.70	1.36	0.25	0.90	1.15	9.35	1.40	7.43	5.01		10.26	7.81	15.50	2.60	2.79



## 12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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- [2] The term 'short data sheet' is explained in section "Definitions".
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